



MOUNTING FOOTPRINT (EACH PORT, TOP VIEW)

NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL & FINISH: (127-0711-321)
 - 1.1 BODY: GOLD PLATED BERYLLIUM COPPER
 - 1.2 CONTACTS: GOLD PLATED BERYLLIUM COPPER
 - 1.3 INSULATORS: PTFE (TEFLON)
 2. ELECTRICAL SPECIFICATIONS:
 - 2.1 IMPEDANCE: 50 OHMS
 - 2.2 FREQUENCY RANGE: DC - 26.5 GHz
 - 2.3 VSWR: 1.25 MAX (0-18 GHz), 1.50 MAX (18-26.5 GHz)
 - 2.4 WORKING VOLTAGE: 335 VRMS MAX AT SEA LEVEL
 - 2.5 DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS MIN AT SEA LEVEL
 - 2.6 INSULATION RESISTANCE: 5000 MEGOHM MIN
 - 2.7 CONTACT RESISTANCE:
 - CENTER CONTACT: INITIAL 6.0 MILLIOHM MAX, AFTER ENVIRONMENTAL NOT APPLICABLE
 - OUTER CONDUCTOR: INITIAL 2.0 MILLIOHM MAX, AFTER ENVIRONMENTAL NOT APPLICABLE
 - 2.8 CORONA LEVEL: 190 VOLTS MIN AT 70,000 FEET
 - 2.9 RF HIGH POTENTIAL WITHSTANDING VOLTAGE: 325 VRMS MIN AT 4 & 7 MHZ
 3. MECHANICAL SPECIFICATIONS:
 - 3.1 INTERFACE DESIGN: 1AW MIL-STD-348, FIG. 326-2, SERIES SMP, FULL DETENT
 - 3.2 ENGAGEMENT FORCE: 15 LBS MAX PER POSITION
 - 3.3 DISENGAGEMENT FORCE: 5 LBS MIN PER POSITION
 - 3.4 CONTACT RETENTION: 1.5 LBS MIN AXIAL
 - 3.5 DURABILITY: 100 CYCLES MIN
 4. ENVIRONMENTAL:
 - 4.1 (MEETS OR EXCEEDS THE APPLICABLE PARAGRAPH OF DSCC DWG NO. 94007)
 - 4.2 OPERATING TEMPERATURE: -65°C TO 165°C
 - 4.3 THERMAL SHOCK: MIL-STD-202, METHOD 107, CONDITION B, EXCEPT 165°C HIGH TEMP
 - 4.4 MECHANICAL SHOCK: MIL-STD-202, METHOD 213, CONDITION I
 - 4.5 CORROSION: MIL-STD-202, METHOD 101, CONDITION B
 - 4.6 VIBRATION: MIL-STD-202, METHOD 204, CONDITION D
 - 4.7 MOISTURE RESISTANCE: MIL-STD-202, METHOD 106, EXCEPT STEP 7B OMITTED
- △ REFERENCE DIMENSIONS FOR 50 OHM GROUND CPW LINE, USING ROGERS RO4003, 16 MIL HIGH FREQUENCY CIRCUIT BOARD SUBSTRATE:
- 5.1 TRACE WIDTH = 27.5 MILS
 - 5.2 GROUND GAPS = 10.5 MILS
 - 5.3 CONDUCTOR THICKNESS = 1.4 MILS (INCLUDES PLATING)
 - 5.4 MAINTAIN SOLID GROUND PLANE BELOW HF SUBSTRATE.
 - 5.5 PLACE 16 MIL DIA. GROUND VIAS ON BOTH SIDES OF COPLANAR WAVEGUIDE LINE AT 50 MIL INTERVALS ALONG ENTIRE LENGTH.
 - 5.6 IMMERSION GOLD PLATE (ENIG) ALL CONDUCTORS PER IPC-4552.
 - 5.7 ALL HOLES PLATED THRU ENTIRE CIRCUIT BOARD STACKUP.
 - 5.8 HOLE PATTERNS SYMMETRICAL ABOUT CENTER OF CPW TRACE.

6. PACKAGING:
 - 6.1 127-0711-321: 1 PER BAG

		JOHNSON
		ASSEMBLY, MALE, FD, RAPC SURFACE MT, SMP, 4 POSITION
THIS DRAWING IS THE PROPERTY OF CINCH CONNECTORS. IT IS TO BE USED FOR THE MANUFACTURE OF THE PARTS SPECIFIED HEREON. IT IS NOT TO BE REPRODUCED OR TRANSMITTED IN ANY FORM OR BY ANY MEANS, ELECTRONIC OR MECHANICAL, INCLUDING PHOTOCOPYING, RECORDING, OR BY ANY INFORMATION STORAGE AND RETRIEVAL SYSTEM, WITHOUT THE WRITTEN PERMISSION OF CINCH CONNECTORS.	PART NO. 127-0711-321/330	DATE 11/16/15
INTERPRETATION OF THIS DRAWING IS THE RESPONSIBILITY OF THE USER.	DRAWN BY B	1 OF 1